

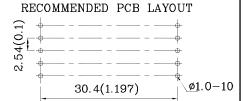
25.4mm (1.0 ") SINGLE DIGIT NUMERIC DISPLAY

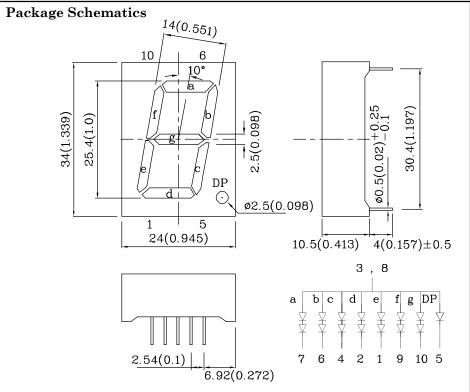
Features

- Low power consumption
- ullet Robust package
- I.C. Compatible
- Standard configuration: Gray face w/ white segments
- Optional black face provides superior color contrast
- RoHS Compliant









Notes:

1. All dimensions are in millimeters (inches), Tolerance is \pm 0.25(0.01")unless otherwise noted.

2. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)		VG (AlGaInP)	Unit	
Reverse Voltage (Per Chip)	$V_{\rm R}$	5	V	
Forward Current (Dp)	I_{F}	30 (30)	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width (Dp)	i_{FS}	150 (150)	mA	
Power Dissipation (Per Chip)	P_D	75	mW	
Operating Temperature	$T_{\rm A}$	-40 ~ +85	°C	
Storage Temperature	Tstg	-40 ~ +85		
Lead Solder Temperature [2mm Below Package Base]	260°C For 3-5 Seconds			

Operating Characteristics (T _A =25°C)		VG (AlGaInP)	Unit
Forward Voltage (Typ.) (Dp) (I _F =10mA)	V_{F}	4.0 (2.0)	V
Forward Voltage (Max.) (Dp) (I _F =10mA)	V_{F}	5.0 (2.5)	V
Reverse Current (Max.) (Per Chip) $(V_R=5V)$	I_R	10 (10)	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =10mA)	λP	574*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I _F =10mA)	λD	570*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =10mA)	Δλ	20	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	15	pF

Part Number	Emitting Color	Emitting Material	Luminous Intensity CIE127-2007* (IF=10mA) ucd		Wavelength CIE127-2007* nm λP	Description
			min.	typ.		
XDVG25A	Green	AlGaInP	52000 14000*	94990 32990*	574 *	Common Anode, Rt. Hand Decimal.

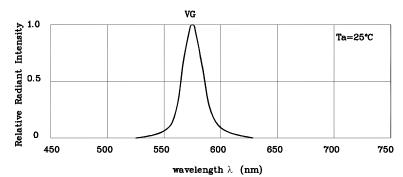
^{*}Luminous intensity value and wavelength are in accordance with CIE127-2007 standards. Jan $18,\!2014$

XDSB7708 V1-X Layout: Maggie L.



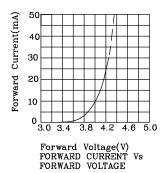


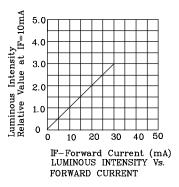
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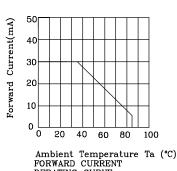


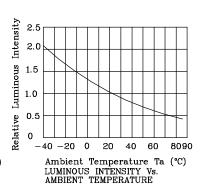
RELATIVE INTENSITY Vs. CIE WAVELENGTH

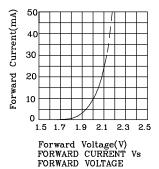
❖ VG

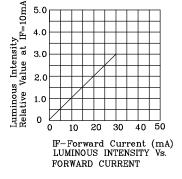


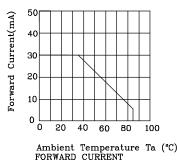




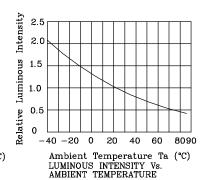




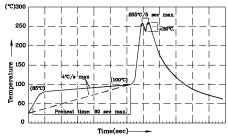




DERATING CURVE



Wave Soldering Profile for Thru-Hole Products (Pb-Free Components)



- Notes:

 1. Recommend pre-heat temperature of 105°C or less (as measured thermocouple attached to the LED pins) prior to immersion in the wave with a maximum solder bath temperature of 260°C

 2. Peak wave soldering temperature between 245°C ~ 255°C for 3 sc
- 2.Peak wave soldering temperature outman, 3.Do not apply stress to the epoxy resin 4.Fixtures should not incur stress on the during soldering process.
 5.SAC 305 solder alloy is recommended.
 6.No more than one wave soldering pass.

Remarks:

DERATING CURVE

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength),

the typical accuracy of the sorting process is as follows:

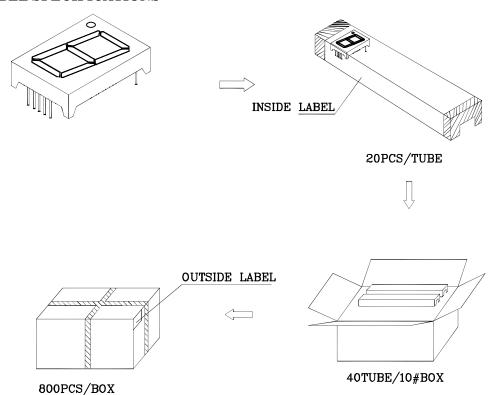
- 1. Wavelength: +/-1nm
- 2. Luminous Intensity / Luminous Flux: +/-15%
- 3. Forward Voltage: +/-0.1V

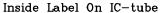
Note: Accuracy may depend on the sorting parameters.

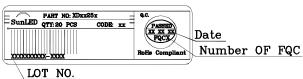




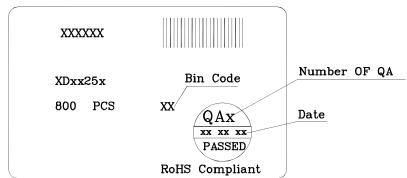
PACKING & LABEL SPECIFICATIONS







Outside Label On Box



TERMS OF USE

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- 2. Contents within this document are subject to improvement and enhancement changes without notice.
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- $6. \ Additional\ technical\ notes\ are\ available\ at\ \underline{http://www.SunLEDusa.com/TechnicalNotes.asp}$

Jan 18,2014